

SS12FL THRU SS16FL

Surface Mount Schottky Barrier Rectifier

Reverse Voltage - 20 and 60 V Forward Current - 1.0 A

FEATURES

- Metal silicon junction, majority carrier conduction
- For surface mounted applications
- Low power loss, high efficiency
- High forward surge current capability
- For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications

MECHANICAL DATA

• Case: SMAF

• Terminals: Solderable per MIL-STD-750, Method 2026

• Approx. Weight: 27mg 0. 00086oz

Absolute Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz resistive or inductive load, for capacitive load, derate by 20 %

Parameter	Symbols	SS12FL	\$\$14FL	\$\$16FL	Units	
Maximum Repetitive Peak Reverse Voltage	V _{RRM}	20	40	60	V	
Maximum RMS voltage	V _{RMS}	14	28	42	V	
Maximum DC Blocking Voltage	V _{DC}	20	40	60	V	
Maximum Average Forward Rectified Current	I _{F(AV)}	1.0				
Peak Forward Surge Current,8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I _{FSM}	40				
Max Instantaneous Forward Voltage at 1 A	V _F	0.4	0.50	V		
Maximum DC Reverse Current T _a = 25°C at Rated DC Reverse Voltage T _a =100°C	I _R	0.3 10				
Typical Junction Capacitance 1>	Cj	180 80				
Typical Thermal Resistance 2)	R _{eja}	115				
Operating Junction Temperature Range	Tj	-55 ~ +125				
Storage Temperature Range	T _{stg}	-55~+150				

1) Measured at 1MHz and applied reverse voltage of 4 V D.C. 2) P.C.B. mounted with 0.2 X 0.2" (5 X 5 mm) copper pad areas.

PINNING

PIN	DESCRIPTION				
1	Cathode				
2	Anode				





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Fig.1 Forward Current Derating Curve

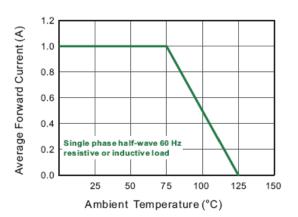


Fig.2 Typical Reverse Characteristics

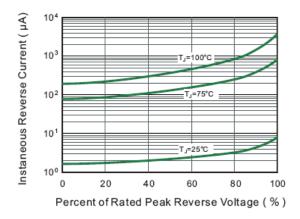


Fig.3 Typical Forward Characteristic

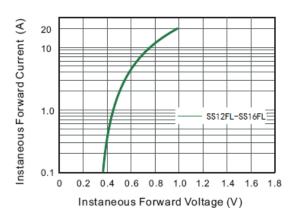


Fig.4 Typical Junction Capacitance

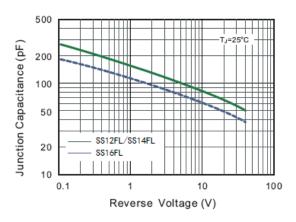


Fig.5 Maximum Non-Repetitive Peak Forward Surage Current

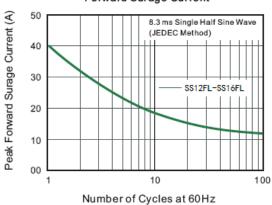
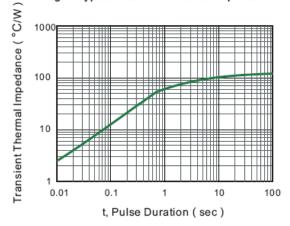


Fig.6-Typical Transient Thermal Impedance



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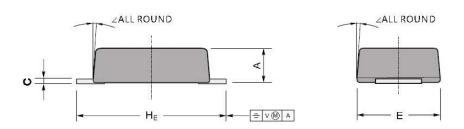


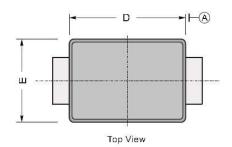
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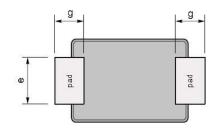
PACKAGE OUTLINE

Plastic surface mounted package; 2 leads

SMAF



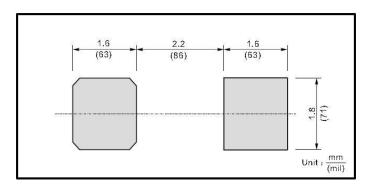




Bottom View

UNIT		Α	O	D	Е	e	9	HE	∠
mm	max	1.1	0.20	3.7	2.7	1.6	1.2	4.9	7°
	min	0.9	0.12	3.3	2.4	1.3	8.0	4.4	
mil	max	43	7.9	146	106	63	47	193	
	min	35	4.7	130	94	51	31	173	

The recommended mounting pad size



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